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IC, Module, and Sytems Design for 100-300GHz MIMO Communications

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Acknowledgements

Systems

Sundeep Rangan — Networks, Applications, MIMO, Power

Upamanyu Madhow, UC Santa Barbara — MIMO algorithms, Imaging algorithms, Compressive imaging

Christoph Studer, Cornell — MIMO algorithms, VLSI MIMO, digital beamforming

Andreas Molisch, USC — 100-300GHz propagation measurements

Danijela Cabric, UCLA — MIMO algorithms (funding via CONIX)

ICs

Ali Niknejad, UC Berkeley — mm-wave CMOS: hub, mm-wave arrays, mm-wave MIMO

Gabriel Rebeiz, UC San Diego — mm-wave CMOS: handset, mm-wave arrays

James Buckwalter, UC Santa Barbara — efficient PAs, III-V arrays

Alyosha Molnar, Cornell — N-path mixers, MIMO ADCs

Kenneth O, UT Dallas — 140-300GHz SiGe ICs

Elad Alon, UC Berkeley — design automation, equalizers

Muhannad Bakir, Georgia Tech — high-frequency packaging

Tim Fisher, UCLA — advanced packaging materials

Andrew Kummel, UCSD — advanced packaging materials

Transistors

Umesh Mishra, UC Santa Barbara — N-polar GaN HEMTs for 140, 210GHz

Huili (Grace) Xing, Cornell — AlN/GaN HEMTs for 140, 210GHz

Susanne Stemmer, UC Santa Barbara — transistors in novel materials

Debdeep Jena, Cornell — GaN HEMTs on Si

Srabanti Chowdhury, UC Davis — Diamond cooling for GaN

Massive MIMO demo. — **Borivoje Nikolic**, UC Berkeley — VLSI design automation, VLSI MIMO processors

Compressive imaging — **Amin Arbabian**, Stanford — 140GHz radar chipsets and arrays

140/210/280GHz arrays for demos. — **Mark Rodwell**, UC Santa Barbara — THz HBTs for PAs, THz HEMTs for LNAs

SRC® JUMP ComSenTer COMMUNICATIONS SENSING TERAHERTZ

ANALOG DEVICES, IBM, arm, NORTHROP GRUMMAN, NSF, Raytheon Technologies, DARPA, tsmc, EMD Performance Materials, LOCKHEED MARTIN, SAMSUNG, SK hynix, Micron, intel, NIST

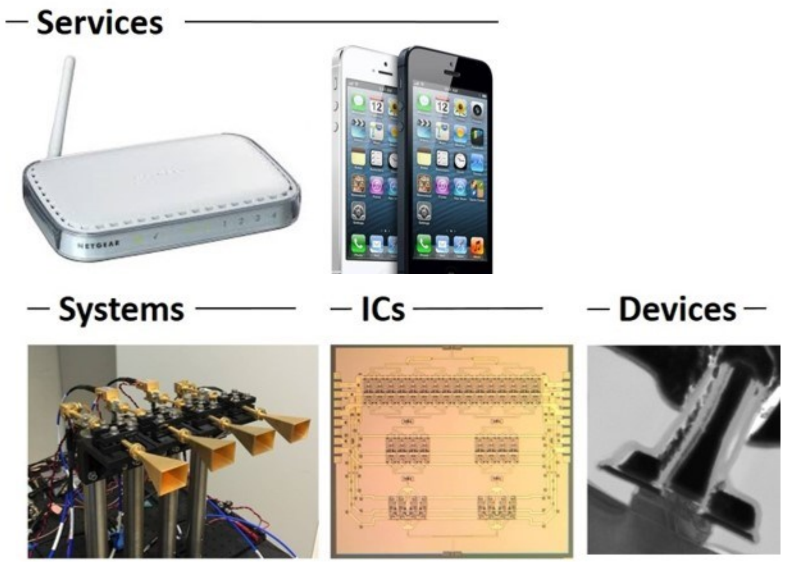
Also:
Kyocera: D. Kim, H. Horikawa, M. Imayoshi.
Samsung: G. Xu, N. Sharma, S. Abu-Surra, W. Choi
Pi-Radio: A. Dhananjay,

100-300GHz Wireless

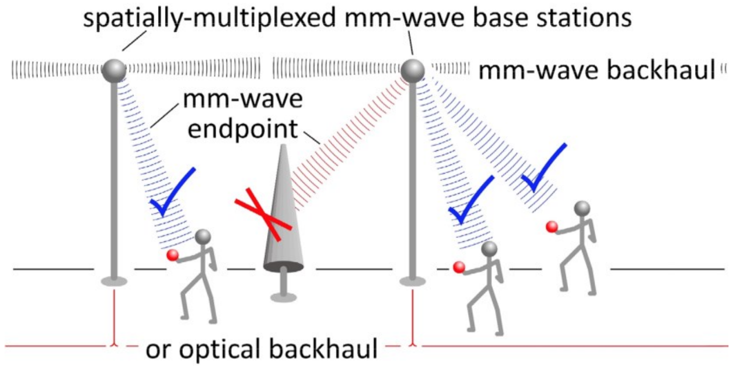
Wireless networks: exploding demand.

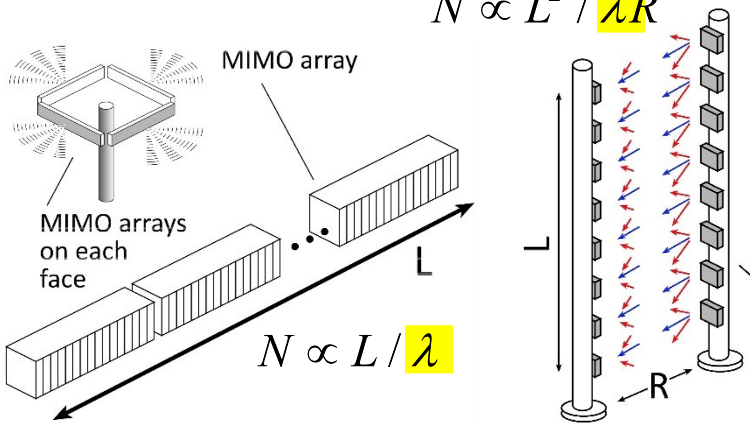
Immediate industry response: 5G.
~1~40 GHz ("5G?")
~40~100GHz ("5.5G ?")
increased spectrum, extensive beamforming

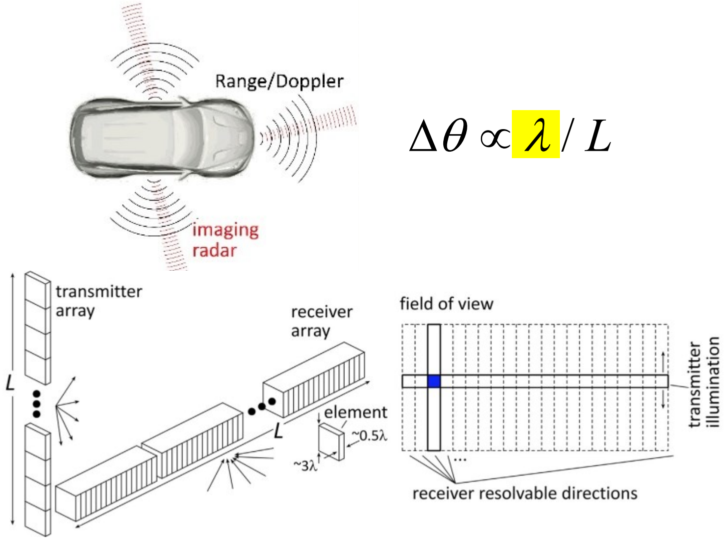
Next generation might be above 100GHz.. (?)
greatly increased spectrum, massive spatial multiplexing



100-300GHz carriers, massive spatial multiplexing
→ Terabit hubs and backhaul links, high-resolution imaging radar

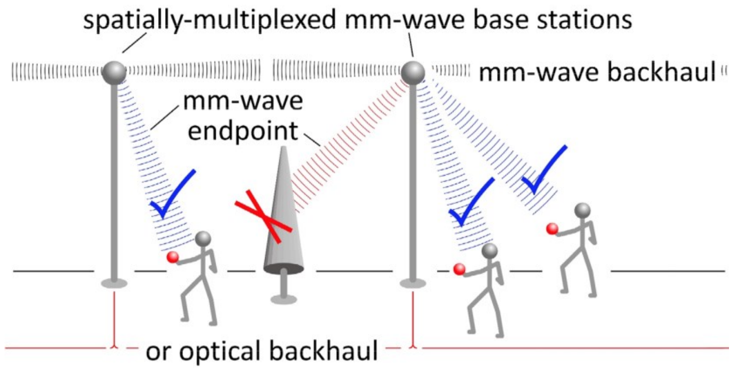


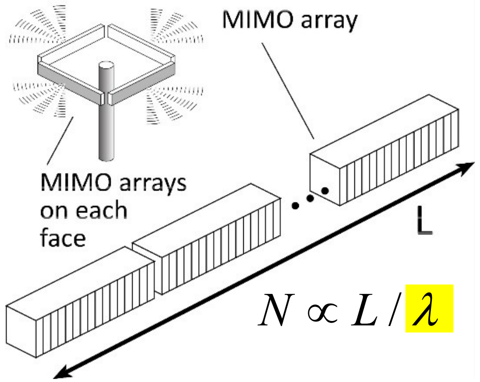


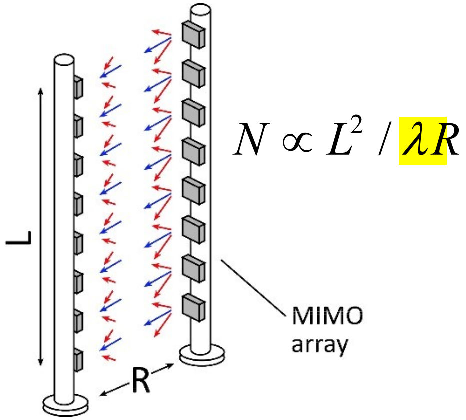


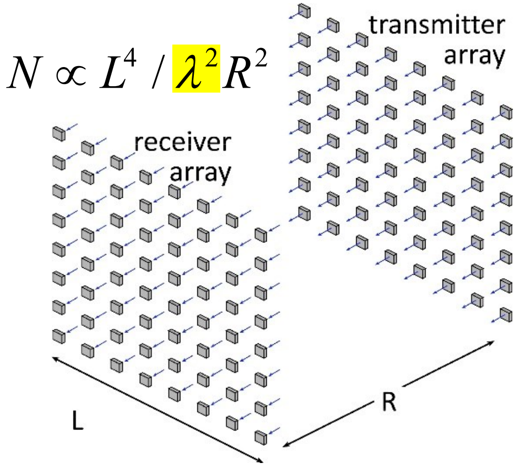
Benefits of Short Wavelengths

Communications: Massive spatial multiplexing, massive # of parallel channels. Also, more spectrum!

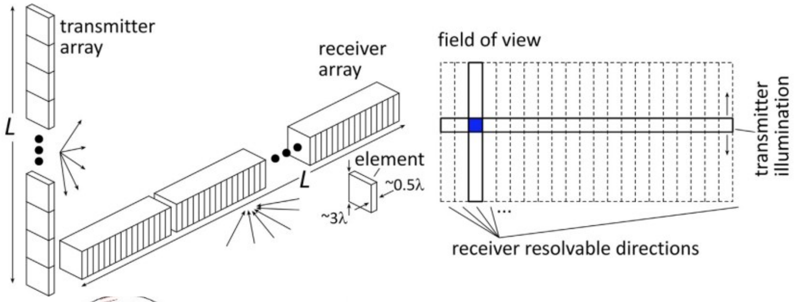


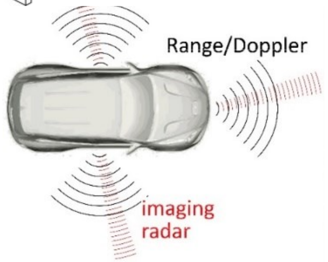






Imaging: very fine angular resolution



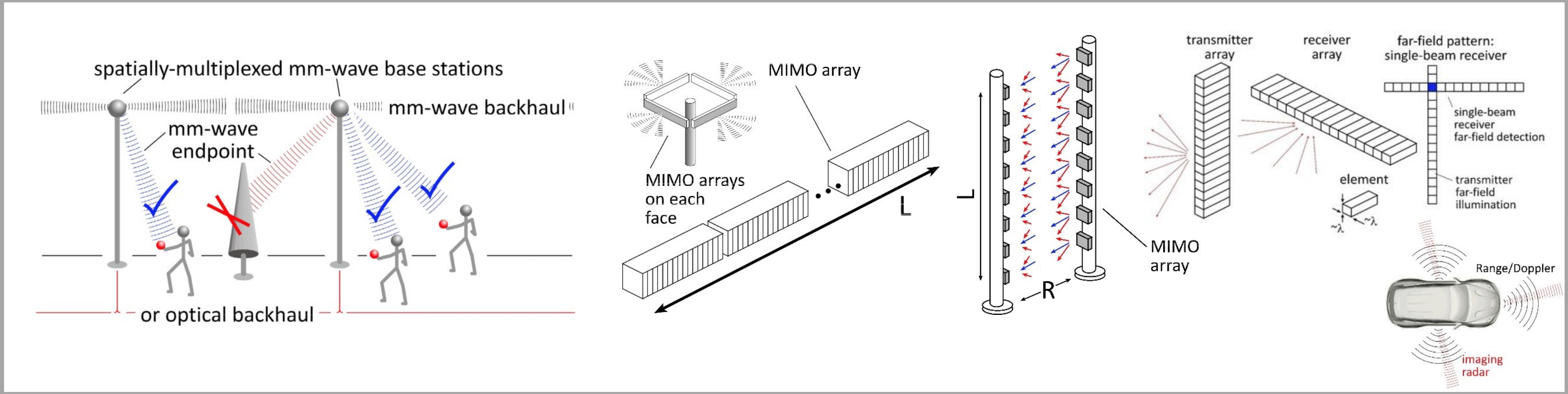


$\Delta\theta \propto \lambda / L$

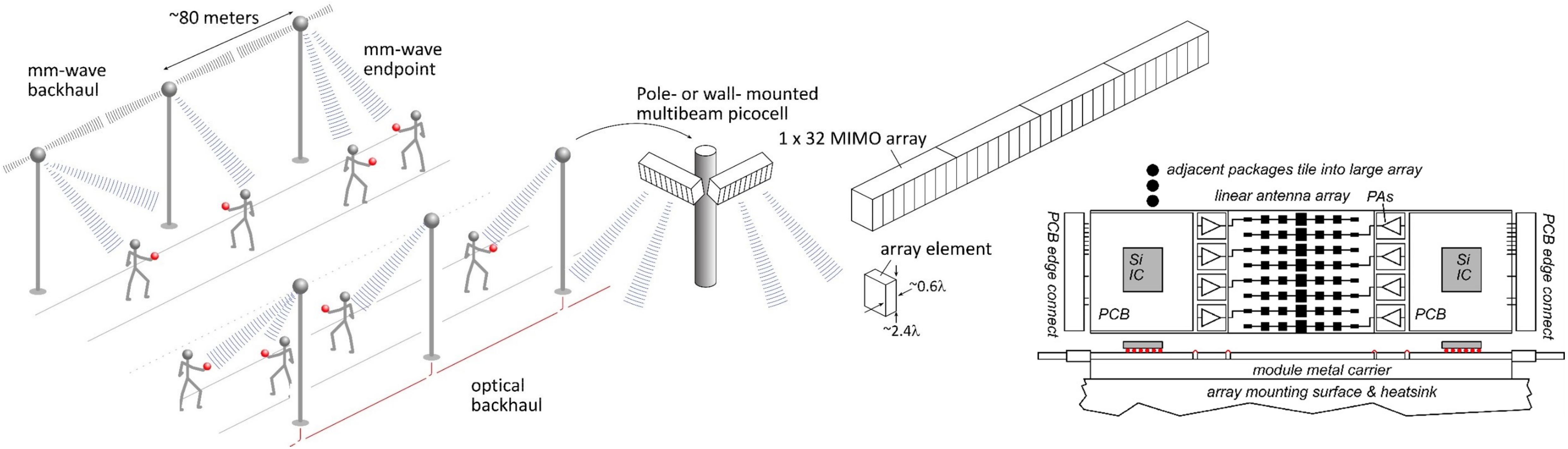
But:
High losses in foul or humid weather.
High λ^2/R^2 path losses.
ICs: poorer PAs & LNAs.
Beams easily blocked.

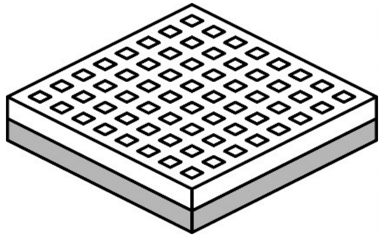
100-340GHz wireless:
terabit capacity,
short range,
highly intermittent

Applications



140GHz moderate-MIMO hub





Handset:
8 × 8 array
(9×9mm)

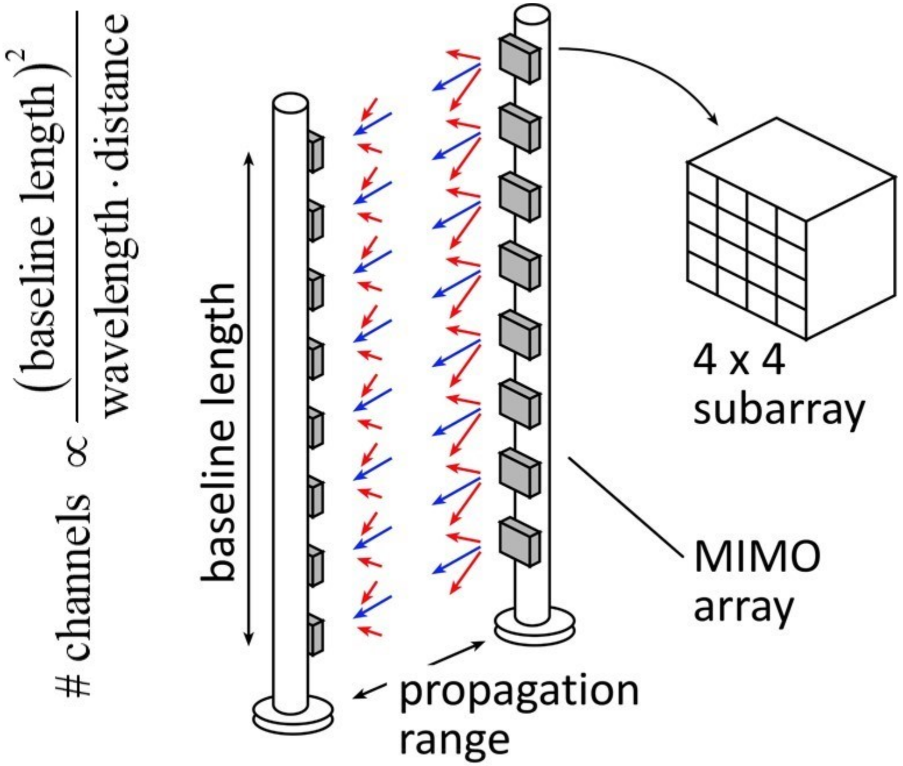
If demo uses 32-element array (four 1×8 modules):

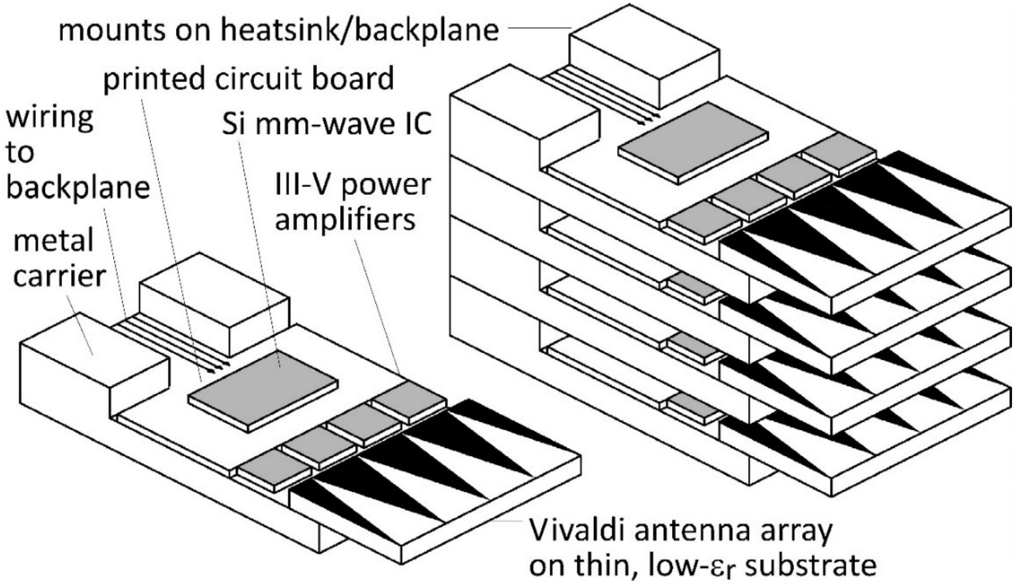
16 users/array. P_{1dB}=21 dB_m PAs, F=8dB LNAs

1,10 Gb/s/beam→ 16, 160 Gb/s total capacity

70, 40 m range in 50mm/hr rain with **17**dB total margins

210 GHz, 640 Gb/s MIMO Backhaul

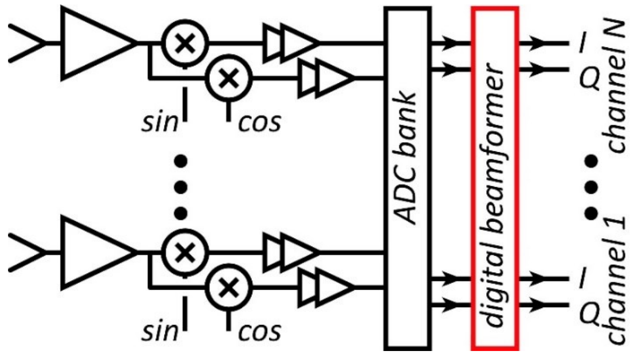


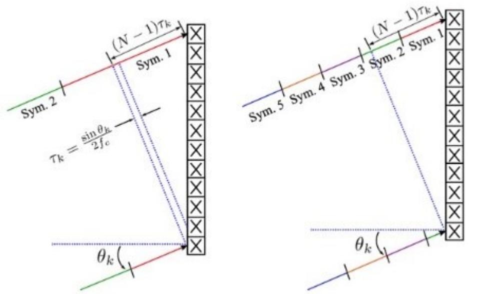


8-element MIMO array
2.1 m baseline.
80Gb/s/subarray→ 640Gb/s total
4 × 4 sub-arrays → 8 degree beamsteering

Key link parameters
500 meters range in 50 mm/hr rain; 23 dB/km
20 dB total margins:
packaging loss, obstruction, operating, design, aging
PAs: 18dBm =P_{1dB} (per element)
LNAs: 6dB noise figure

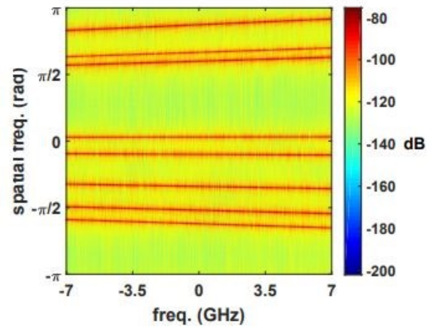
Systems





(a) Narrowband scenario.

(b) Wideband scenario.

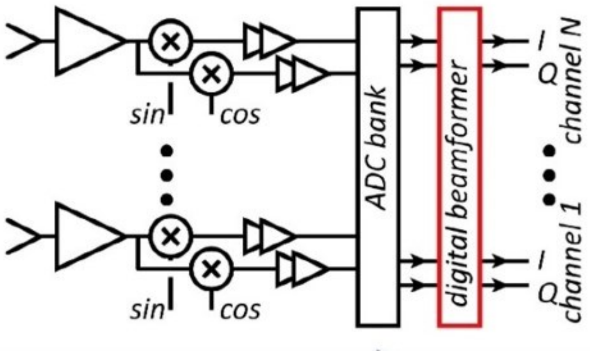


System Design

ADCs/DACs[1]: QPSK needs only 3-4 bit ADC/DACs

N ADC bits, *M* antennas, *K* signals: $SNR=6N+1.76+10\cdot\log_{10}(M/K)$

3 bits, $(M/K)=2 \rightarrow$ SNR=23 dB. QPSK needs 9.8 dB.



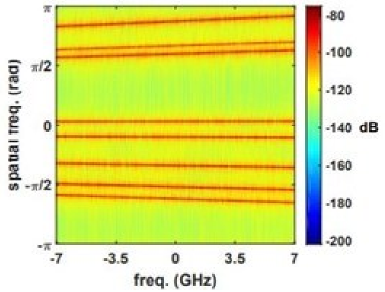
Linearity[1]: Amplifier P_{1dB} need be only 4 dB above average power

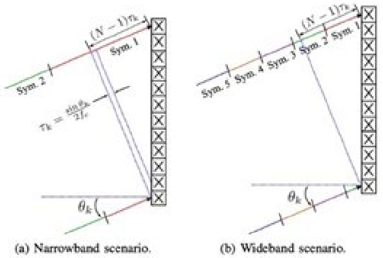
Phase noise[2,3]: Requirements same as for SISO

Efficient digital beamforming[4,5]: beamspace algorithm=complexity ~N× log(N)

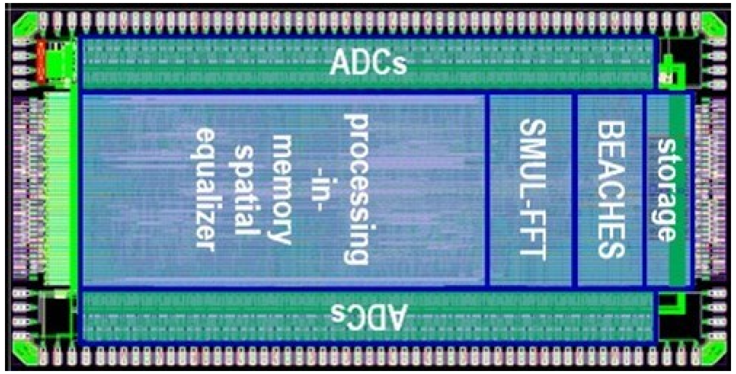
Efficient VLSI digital beamformer implementation[6]: low-resolution matrix

Efficiently beamforming in broadband arrays[7]: combined spatial & temporal FFTs.



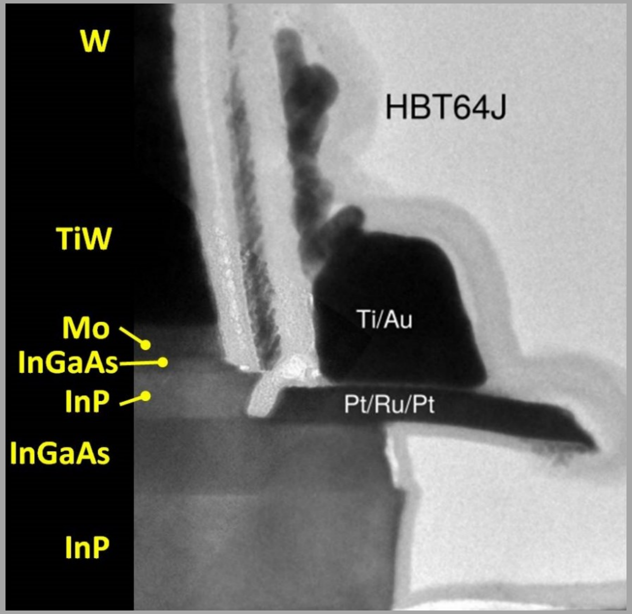


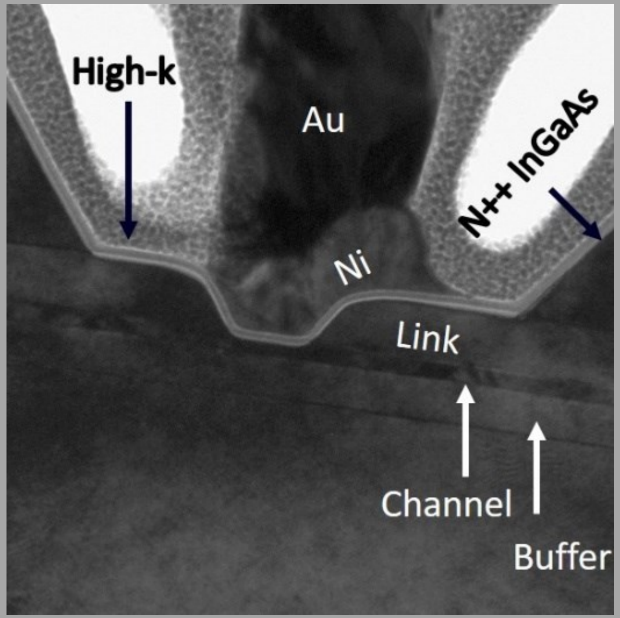
(a) Narrowband scenario. (b) Wideband scenario.

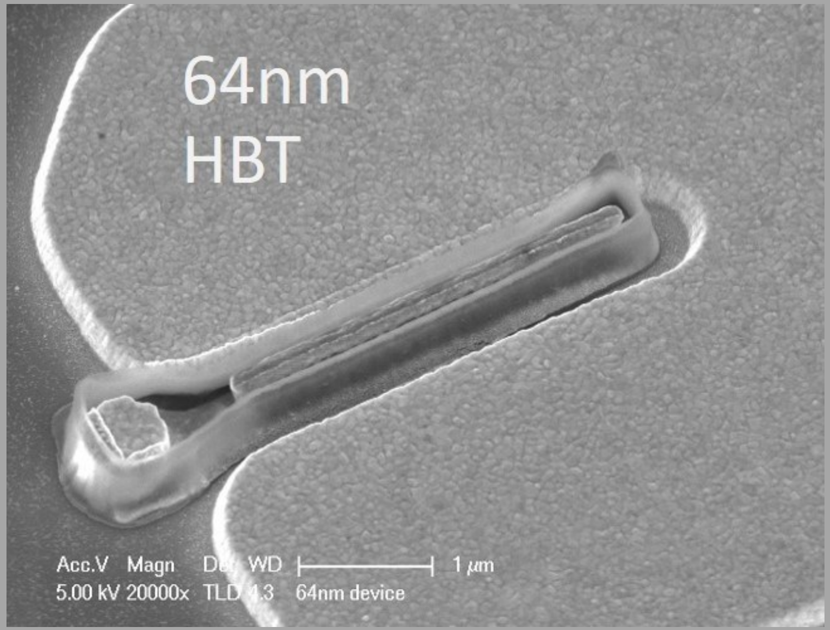


1) M. Abdelghany et al, IEEE Trans. Wireless Comm, Sept. 2021, doi: 10.1109/TWC.2021.3069378.
2) M. E. Rasekh et al, IEEE Trans. Wireless Comm, Oct. 2021, doi: 10.1109/TWC.2021.3074911.
3) A. Puglielli et al, 2016 IEEE ICC, doi: 10.1109/ICC.2016.7511631.
4) M. Abdelghany, et. al, , 2019 IEEE SPAWC: doi: 10.1109/SPAWC.2019.8815585
5) S. H. Mirfarshbafan et al, IEEE Trans CAS 1, 2020, doi: 10.1109/TCSI.2020.3023023
6) O Castañeda Fernández et. al, 2021 ESSCIRC
7) M. Abdelghany et al 2019 IEEE GLOBECOM doi: 10.1109/GLOBECOM38437.2019.9013233.

Transistors







Transistors for 100-300GHz

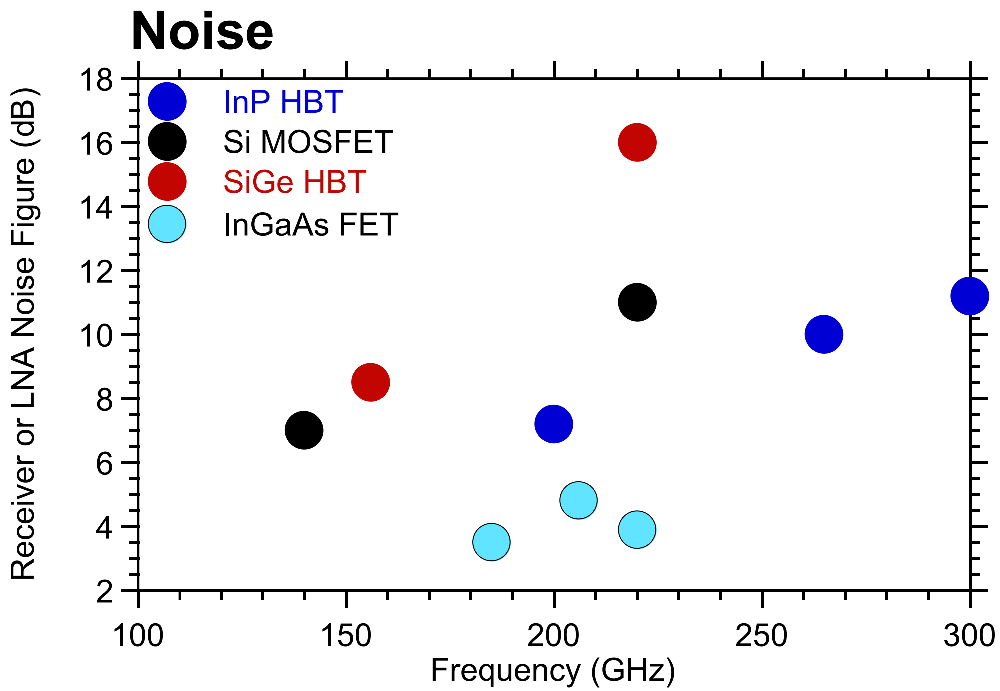
CMOS: good power & noise up to ~150GHz. Not much beyond. 65-22nm nodes are best.

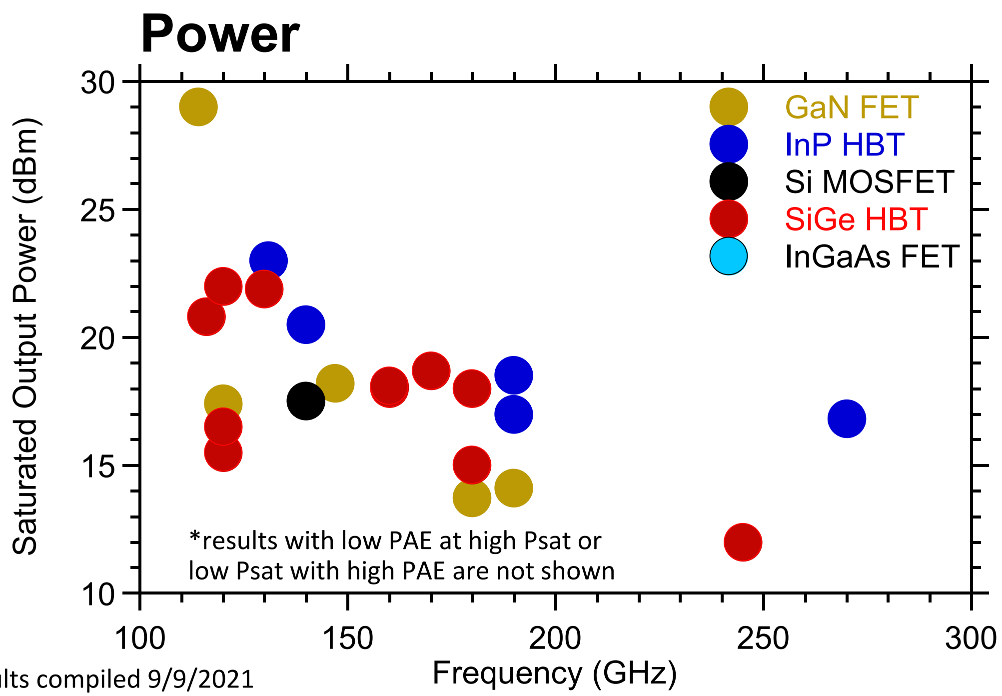
InP HBT: record 100-300GHz PAs

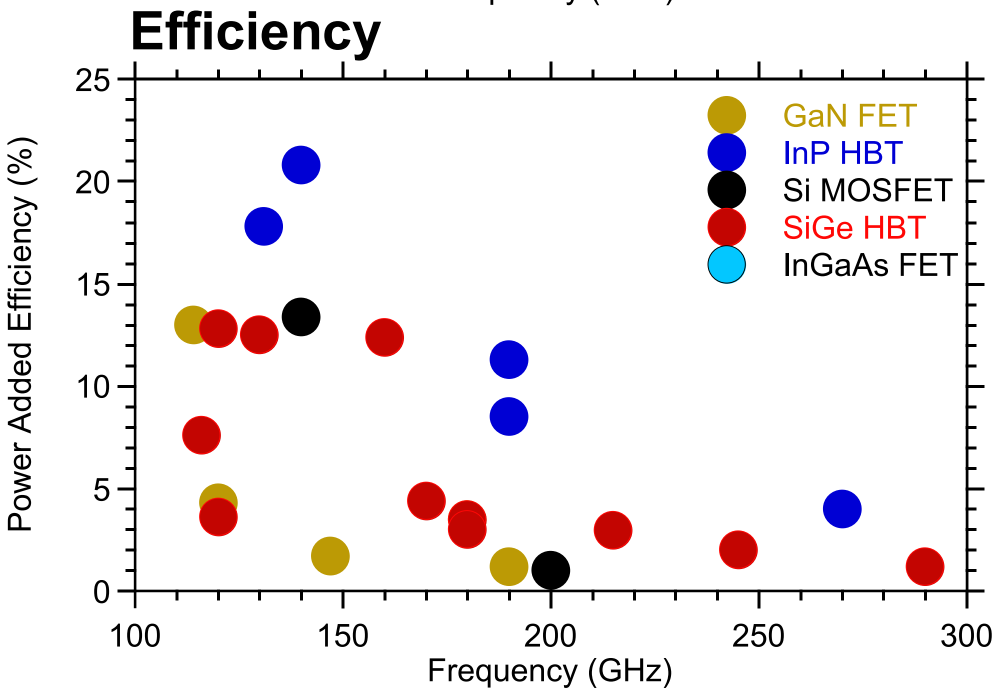
SiGe HBT: power better than CMOS, worse than InP HBT

GaN HEMT: record power below 100GHz. Bandwidth improving

InGaAs-channel HEMT: world's best low-noise amplifiers





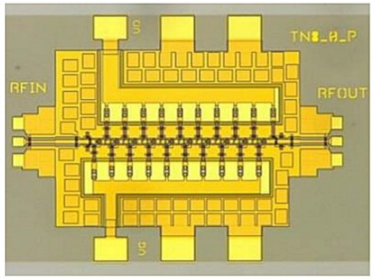


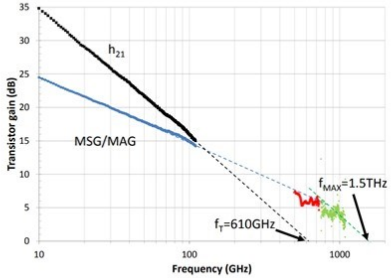
Results compiled 9/9/2021

InP Transistors and ICs

InP HEMTs: 1.5THz f_{max},   1.0THz amplifiers

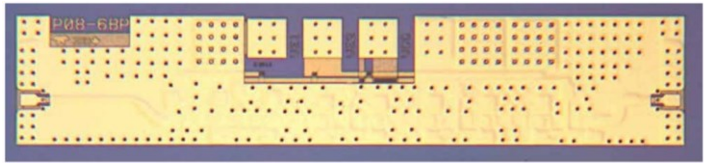
W. Deal et al, 2016 IEDM (Northrop-Grumman)

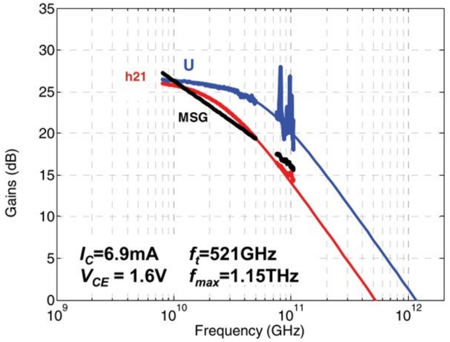


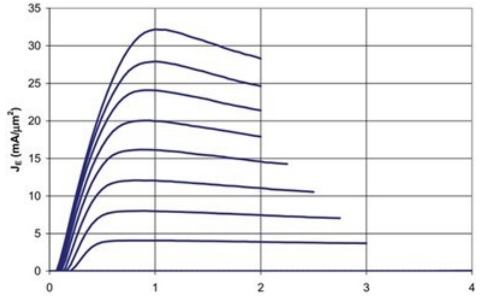


130nm InP HBTs: 1.1THz f_{max}, 3.5V. 670 GHz amplifiers

M. Urteaga, et al, IEEE Proceedings June 2017 (Teledyne)



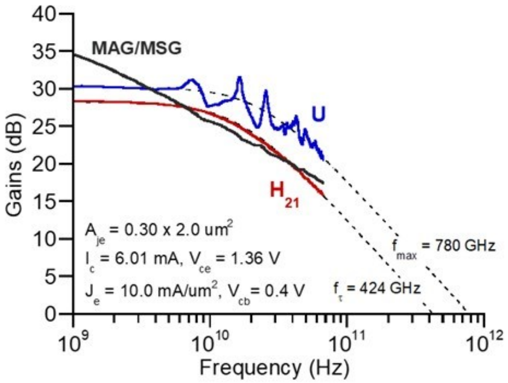


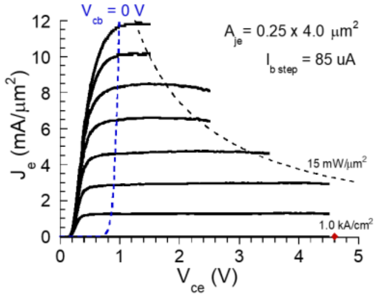


250nm InP HBTs: 650GHz f_{max}, 4.5V.

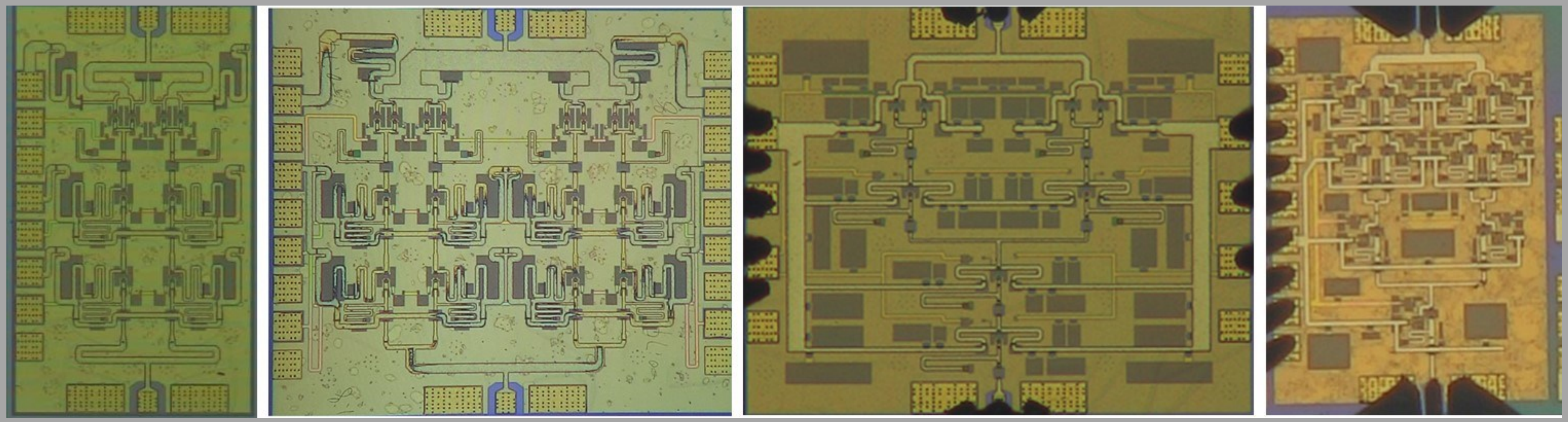
Z. Griffith et al, 2007 IPRM conference (UCSB)

M. Urteaga, et al, IEEE Proceedings June 2017 (Teledyne)





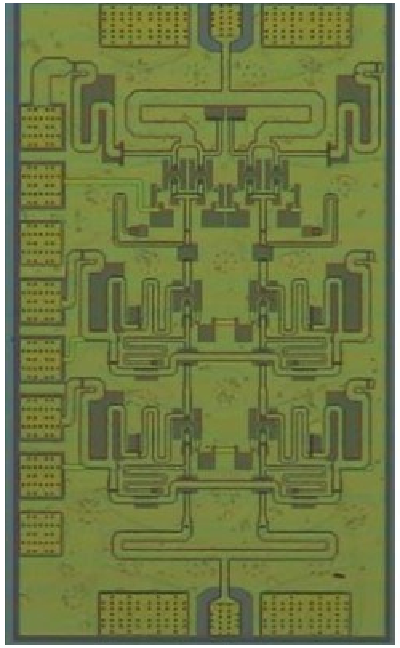
Power Amplifiers

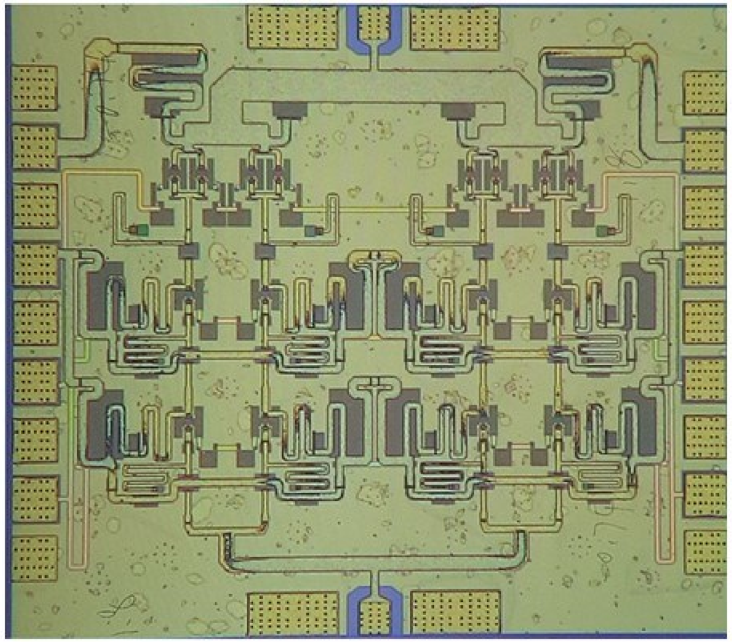


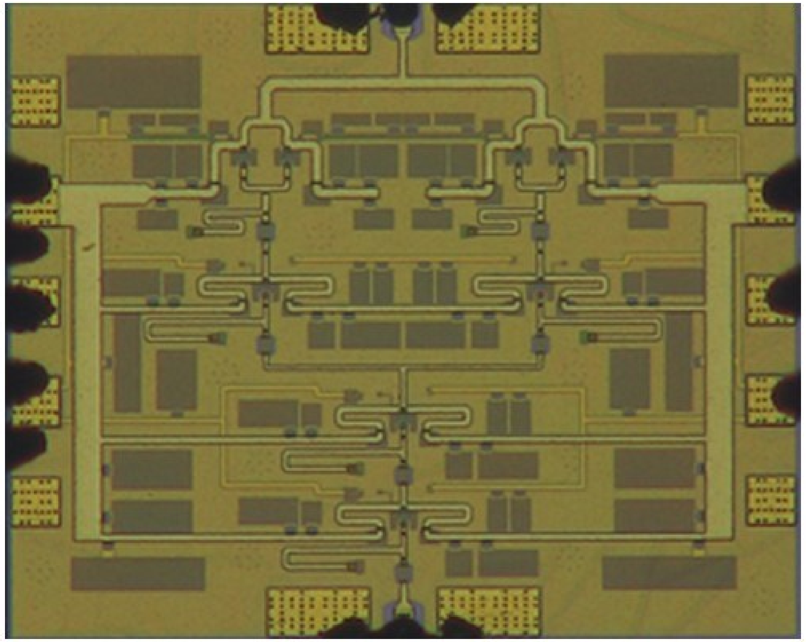
Recent high-efficiency 100-300GHz PAs

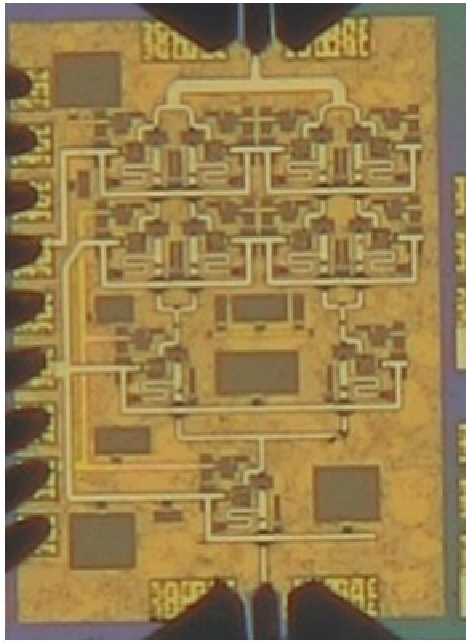
Teledyne 250nm InP HBT technology

Ahmed et al, 2020 IMS, 2020 EuMIC, 2021 IMS, 2021 RFIC







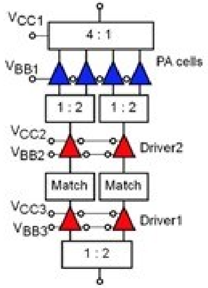


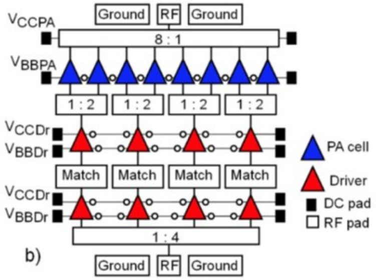
140GHz, 20.5dBm, 20.8% PAE

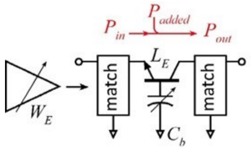
130GHz, 200mW, 17.8% PAE

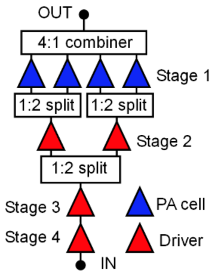
194GHz, 17.4dBm, 8.5% PAE

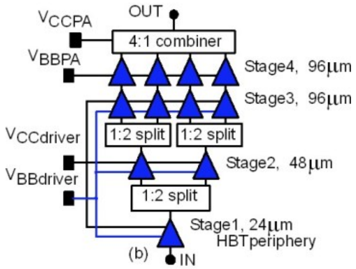
266GHz, 16.8dBm, 4.0% PAE





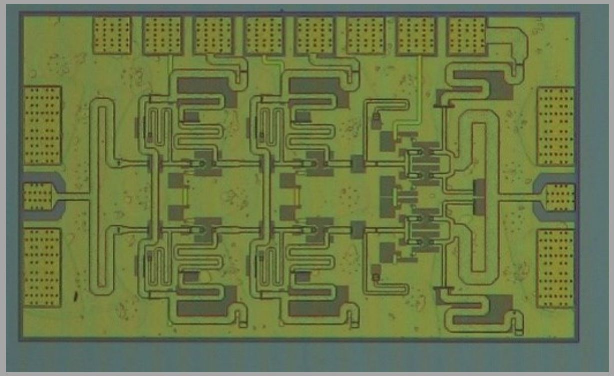


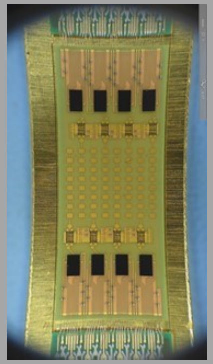




Mixture of corporate and cascade power-combining.

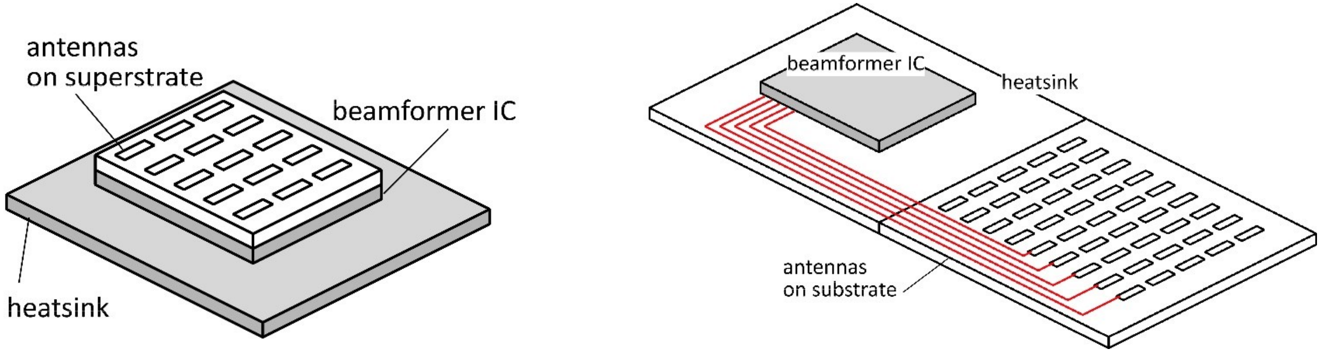
140 GHz
Array Modules





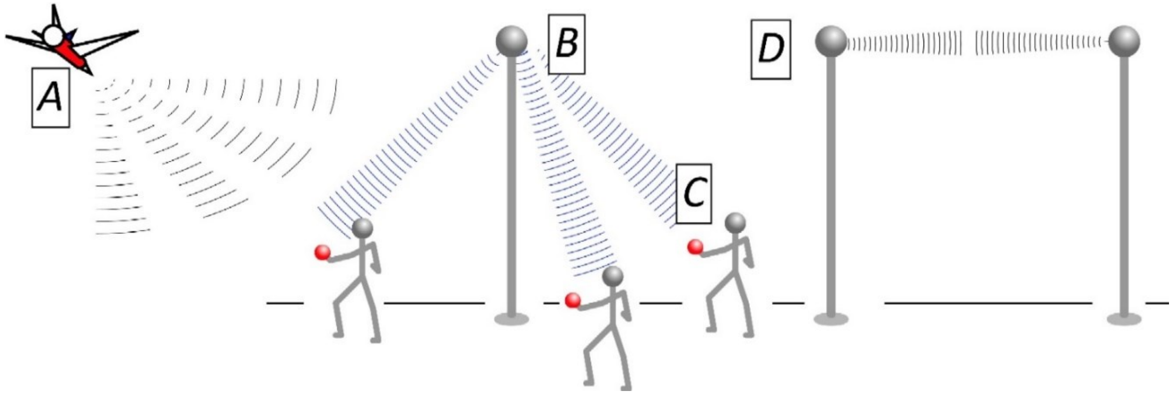
The mm-wave module design problem

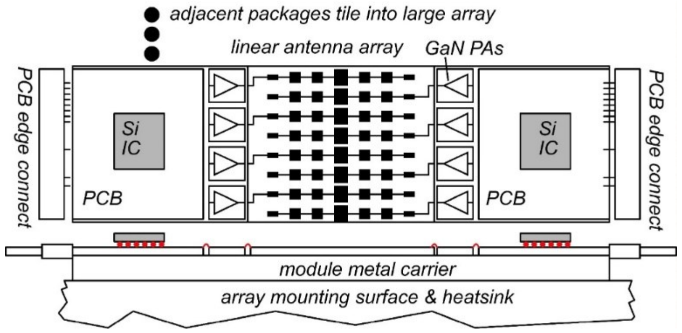
How to make the IC electronics fit ?
How to avoid catastrophic signal losses ?
How to remove the heat ?

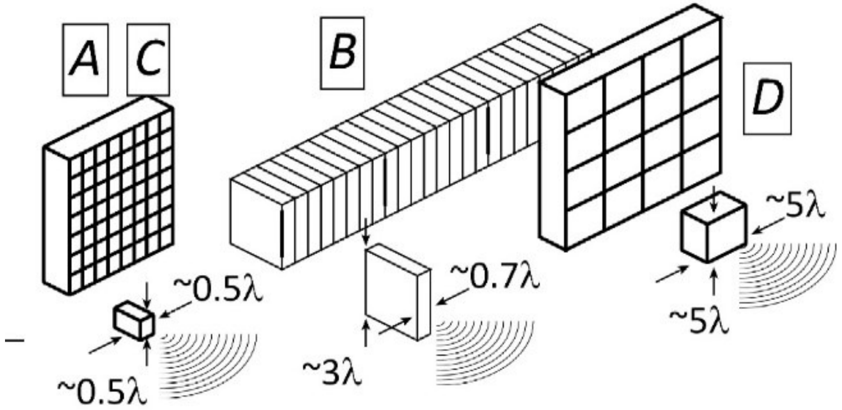


Not all systems steer in two planes...
...some steer in only one.

Not all systems steer over 180 degrees...
...some steer a smaller angular range





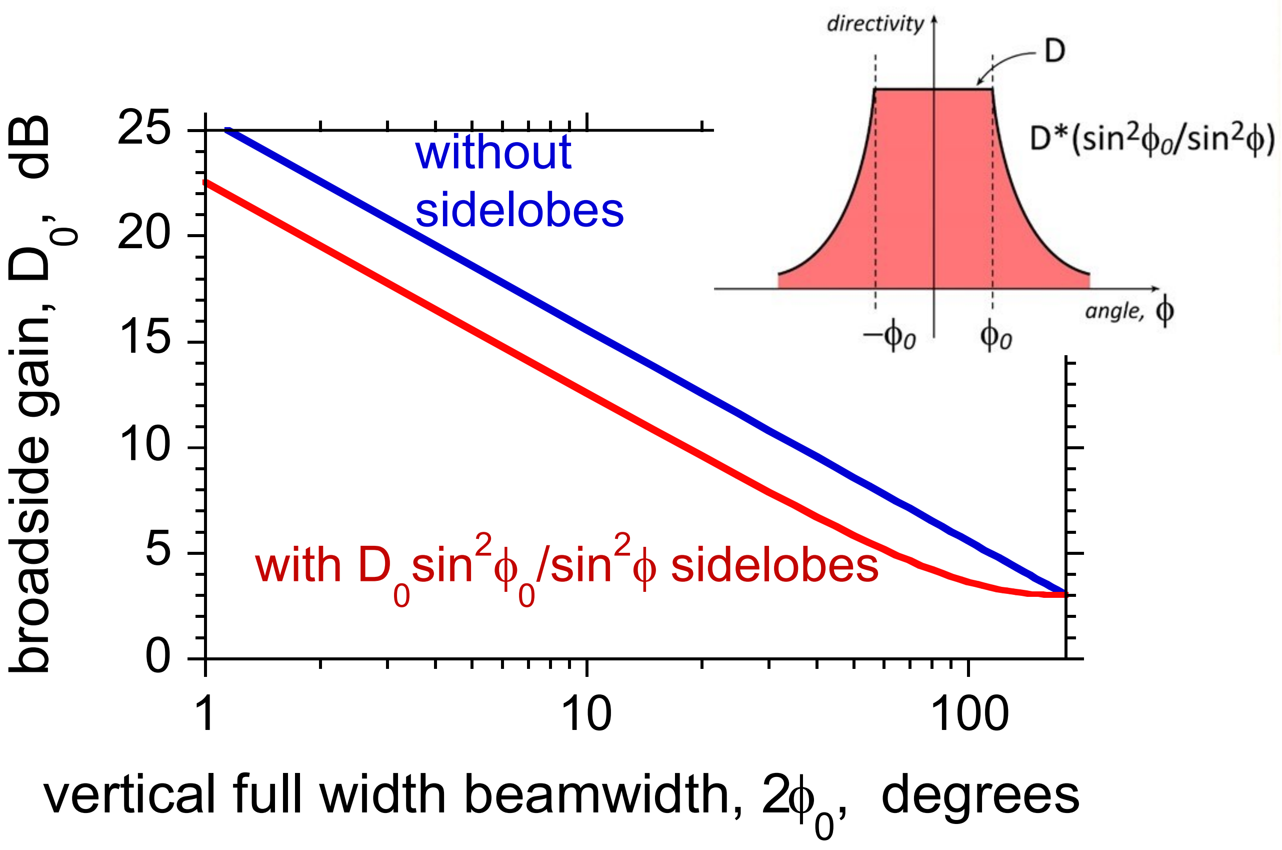


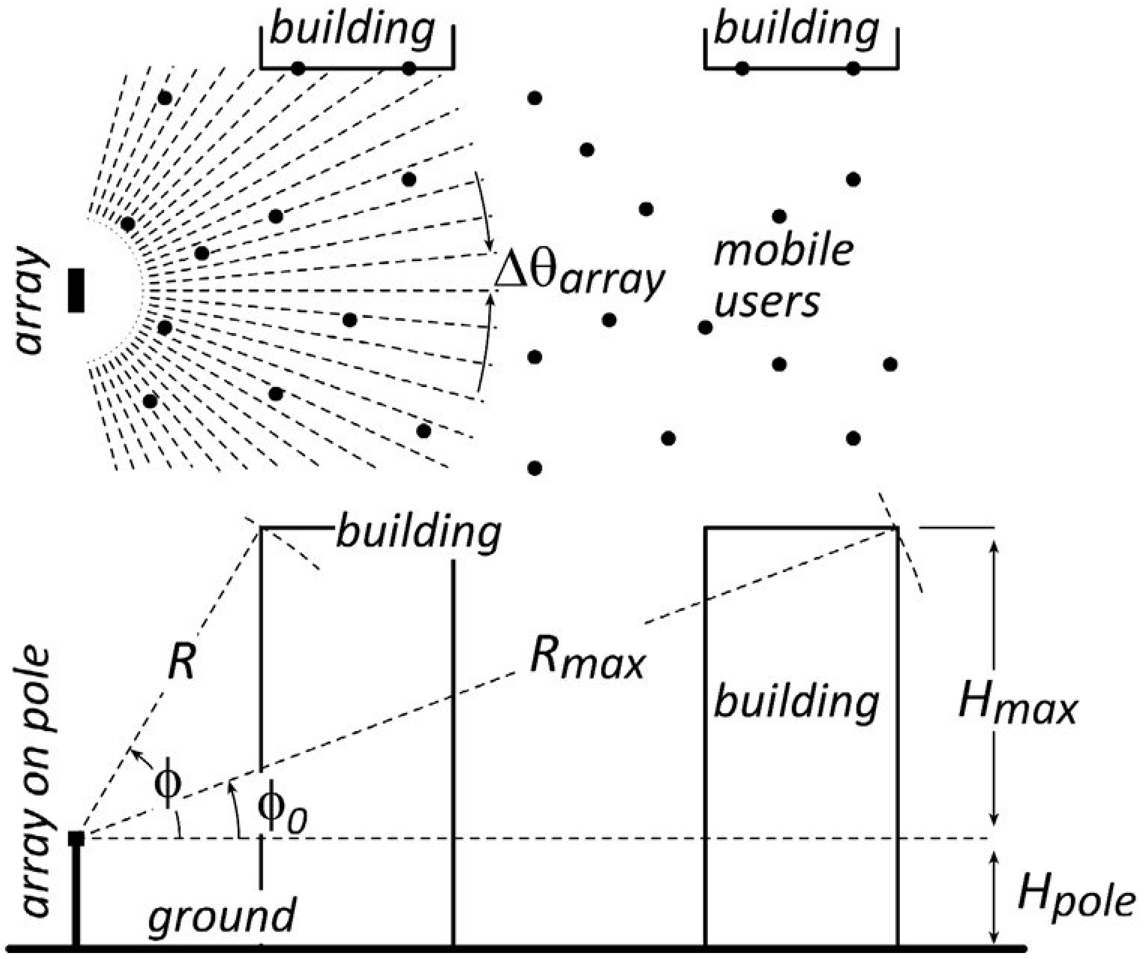
Do we need 2D arrays ? 1D steering might be fine.

$1/\sin^2\phi$ sidelobes provide strong signals to tall buildings.

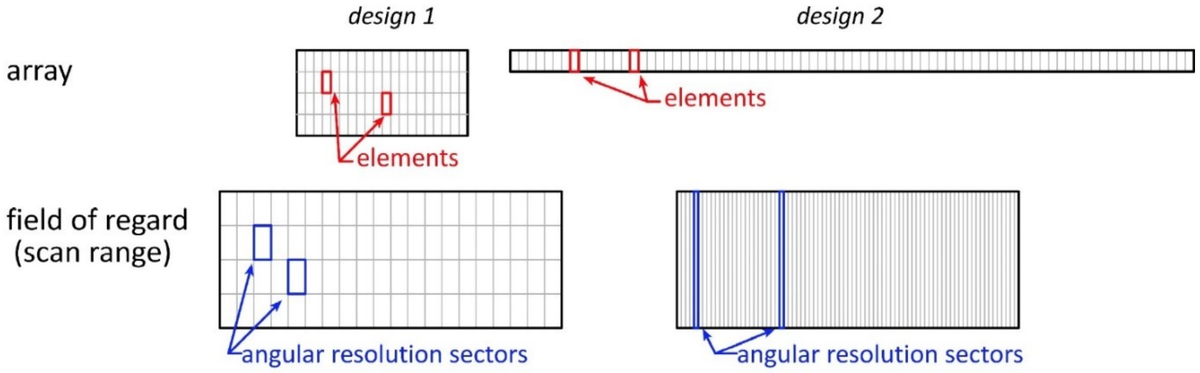
Providing sidelobes reduces broadside gain by less than 3dB.

→ Don't need 2D arrays to serve tall buildings





2D vs. 1D: user spatial distribution

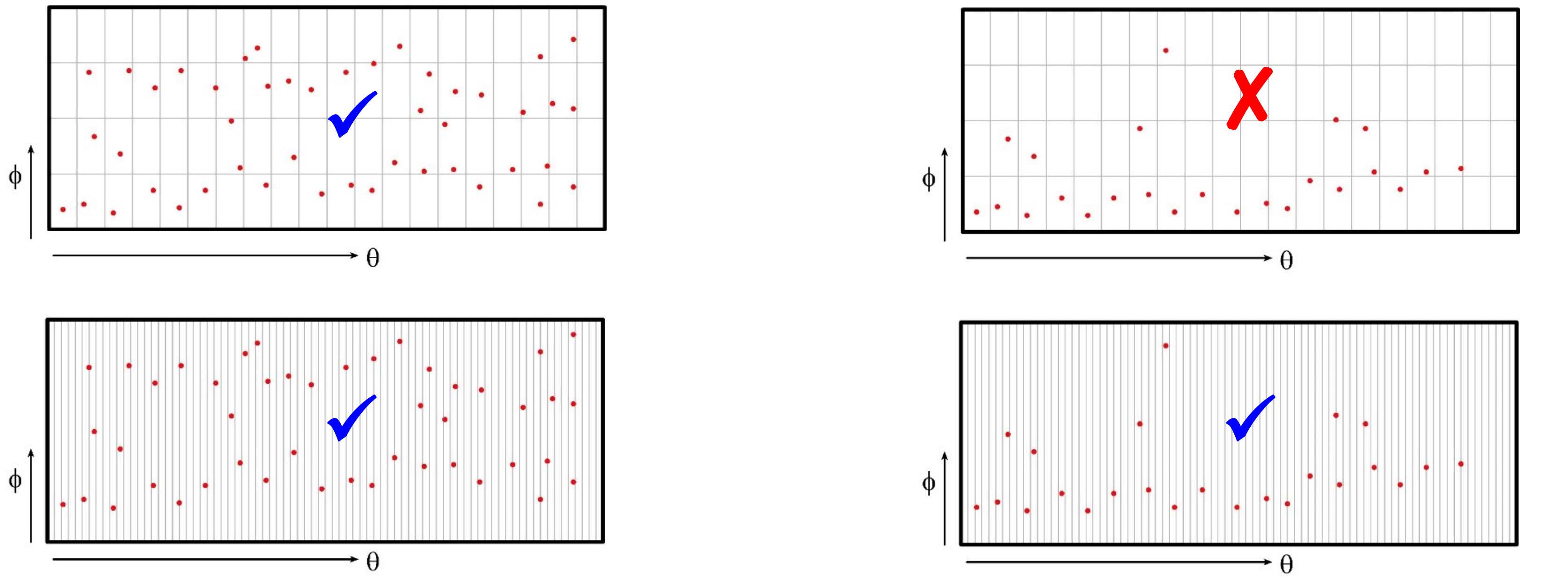


uniform horizontal & vertical user distributions

uniform horizontal, nonuniform vertical

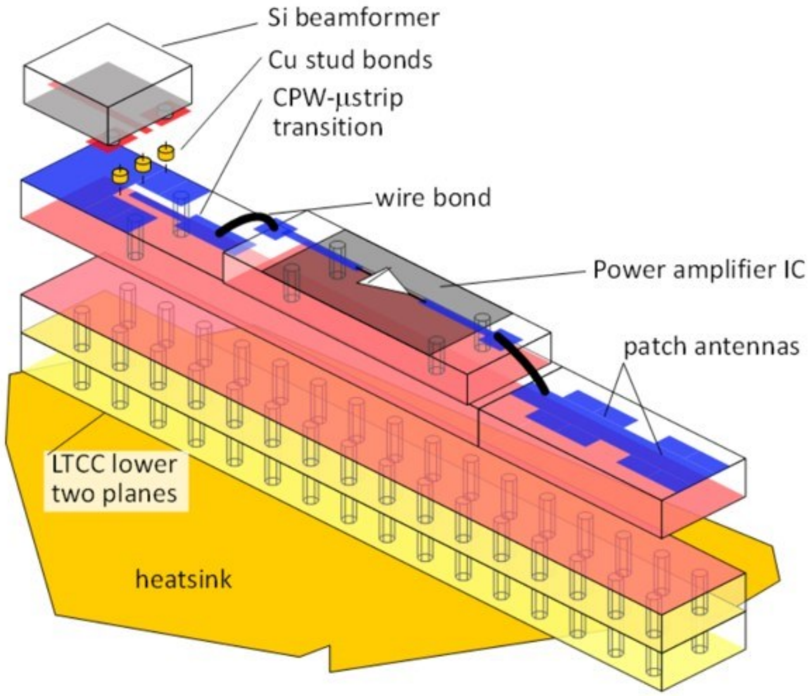
design 1: 2D array

design 2: 1D array

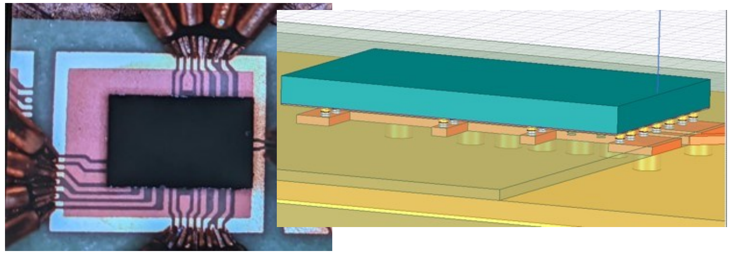


Spatial distribution of users, and of scattering objects, guides choice of array geometry.

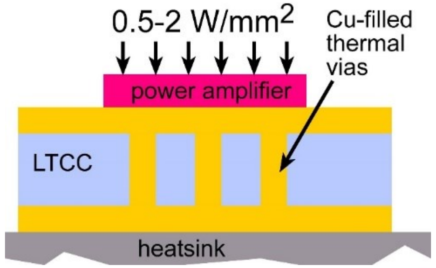
140GHz hub: packaging challenges



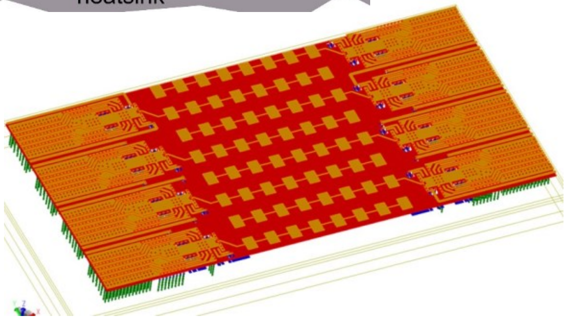
IC-package interconnects
Difficult at > 100 GHz



Removing heat
Thermal vias are marginal



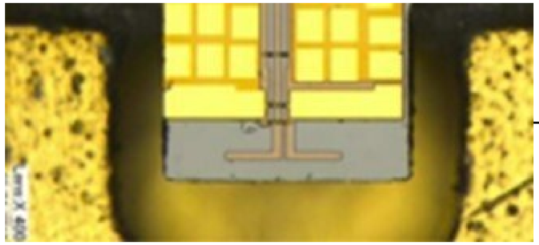
Interconnect density
Dense wiring for DC, LO, IF, control.
Hard to fit these all in.



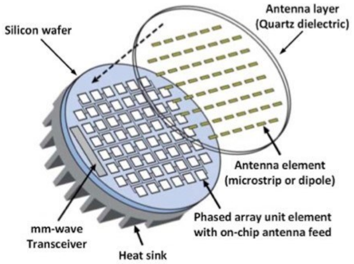
Economies of scale
Advanced packaging standards require sophisticated tools
High-volume orders only
Hard for small-volume orders (research, universities)
Packaging industry is moving offshore

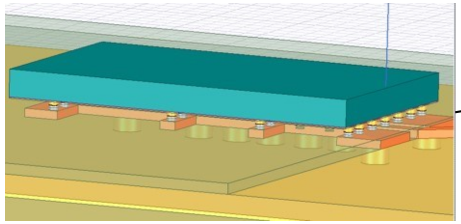
100-300GHz IC-package connections

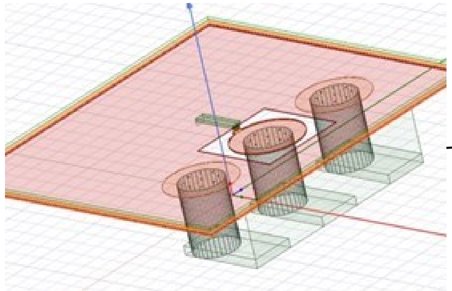
Deal, IEEE Trans THz, Sept 2011



G. Rebeiz







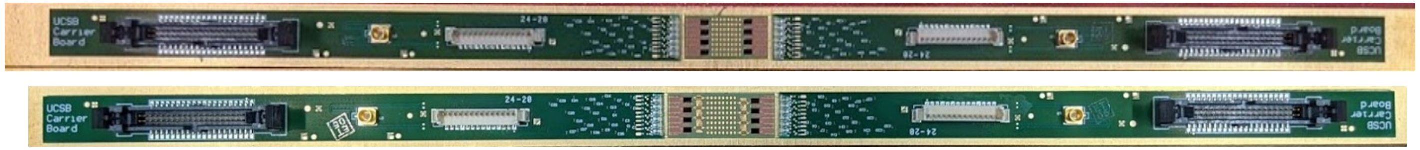
type	Frequency	technology	cost	heatsinking
micromachined waveguide interface	1000 GHz	Research. Cheap one day ?	**high** ✗	good
ribbon, mesh bond	200 GHz	Handcrafted.	**high** ✗	good
patch antennas on superstrate	1000 GHz	Straightforward	low	good
Cu stud flip-chip	>200 GHz	Industry standard	low	ok, **marginal for PA** ✗
hot vias	200 GHz	Development	low ?	good
(ball) wirebonds	**100 GHz** ✗	Industry standard	low	good

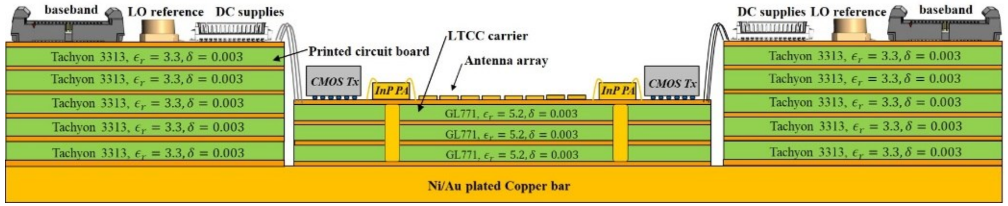
135GHz 8-channel MIMO hub array tile modules

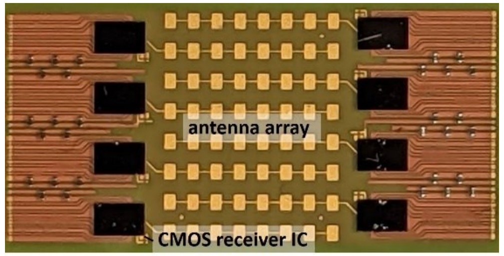
140GHz MIMO hub receiver array modules,
4-element, 8-element
MIMO beamforming
Data transmission up to 1.9Gb/s

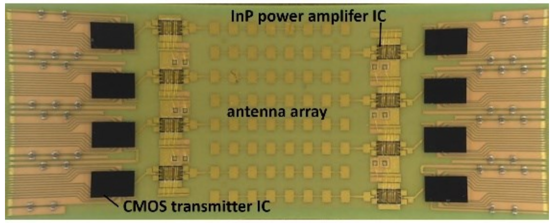
140GHz MIMO hub transmitter array modules,
8-element
results in review

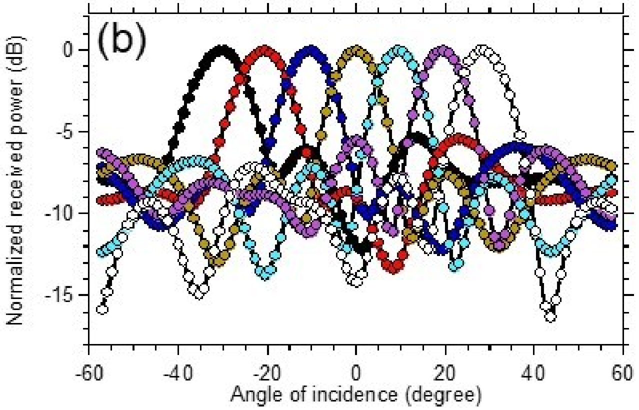
Receiver: A. Farid, 2021 BCICTS; Transmitter: in review

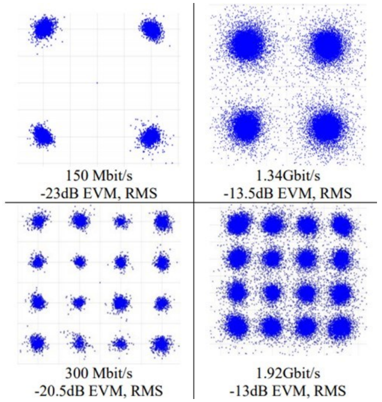




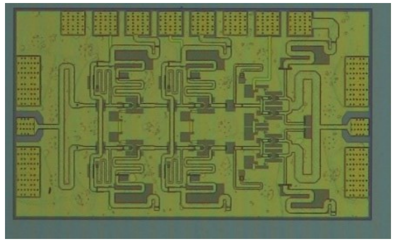






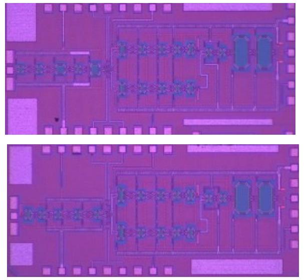


110mW InP PA
20.8% PAE

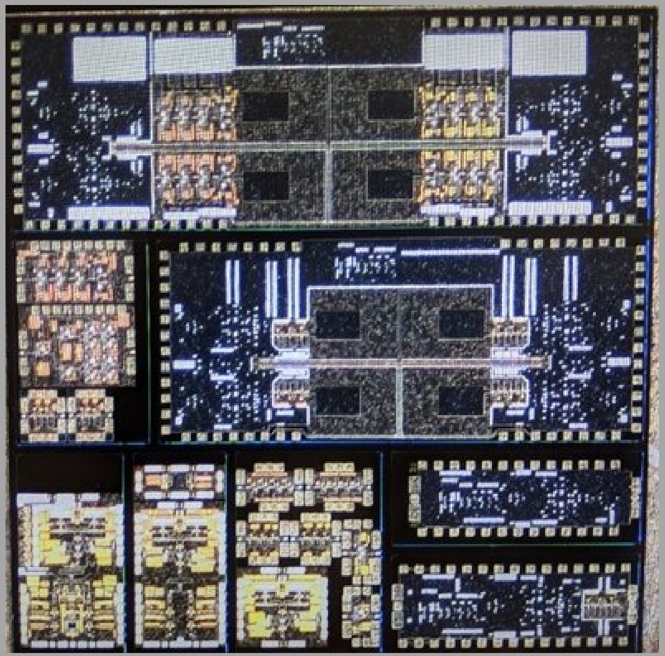


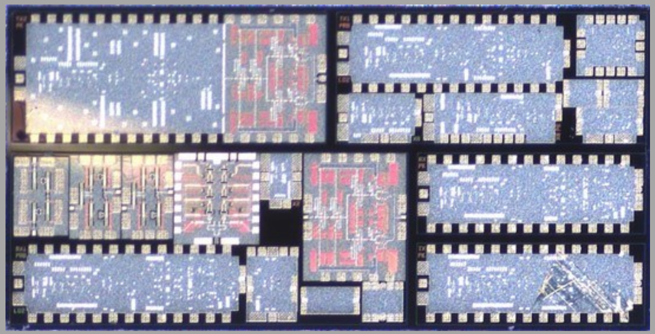
Teledyne 250nm InP HBT

CMOS TX, RX ICs
GlobalFoundries
22nm SOI CMOS.

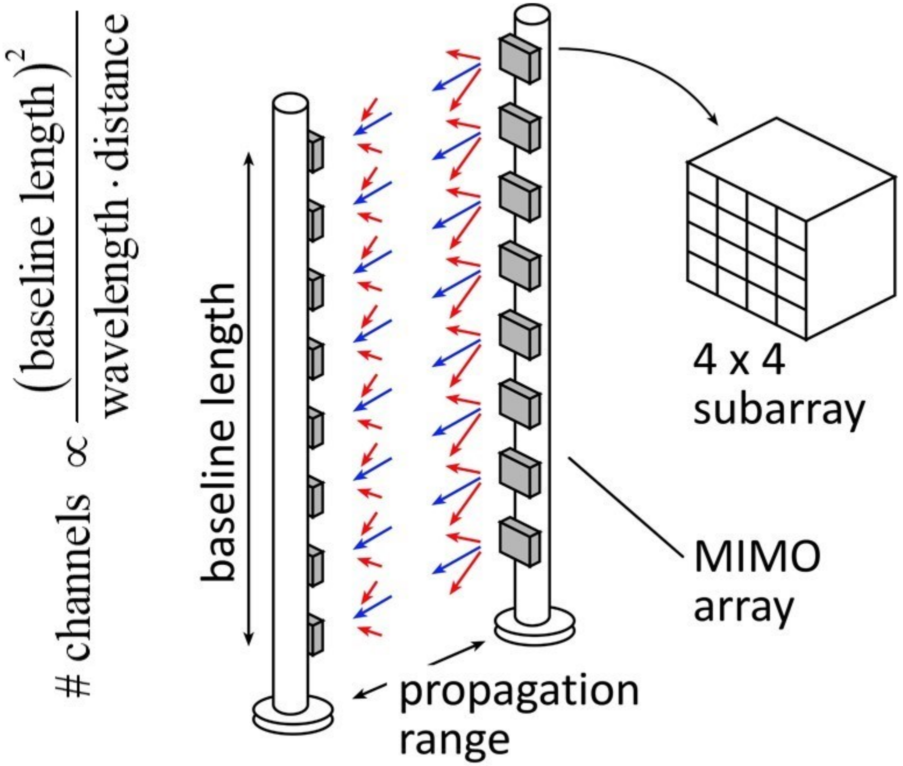


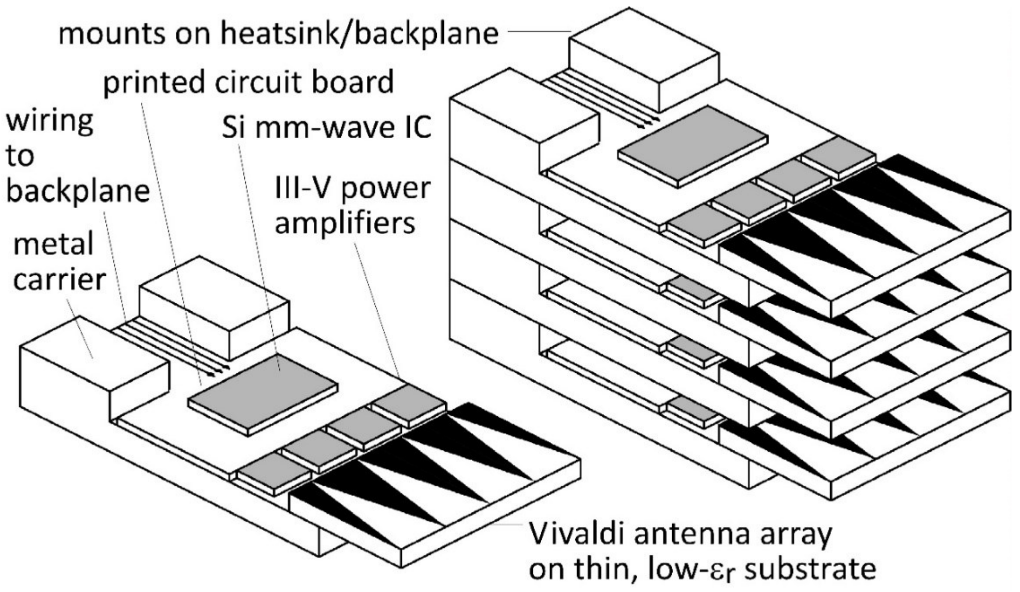
210 GHz and 280 GHz Array Modules





210 GHz MIMO backhaul demo



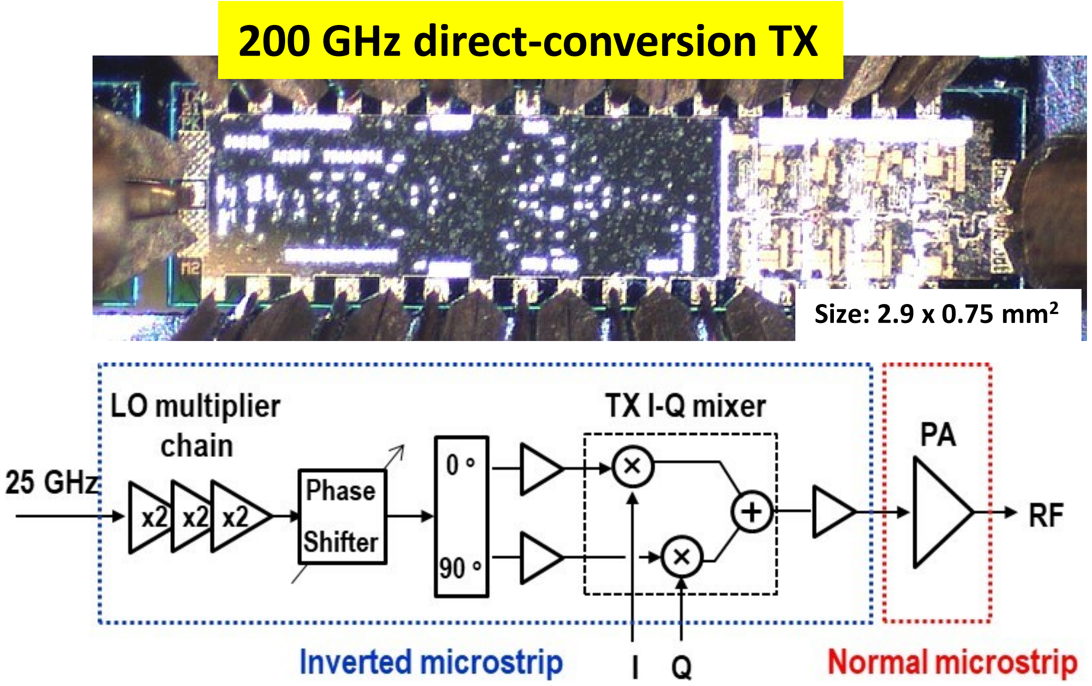


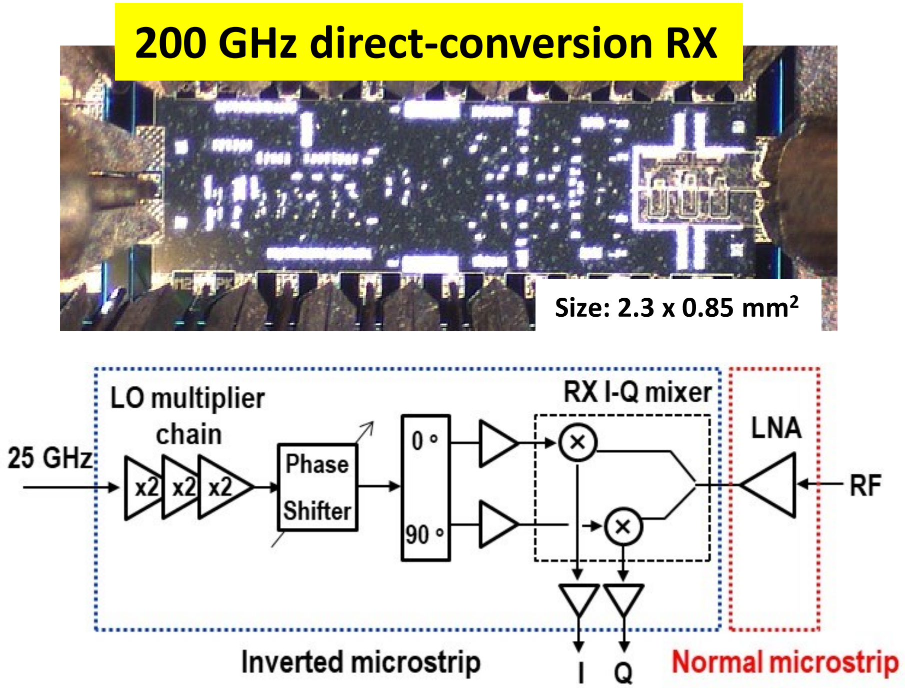
8-element MIMO array
3.1 m baseline for 500m link.
80Gb/s/subarray→ 640Gb/s total
4 × 4 sub-arrays → 8 degree beamsteering

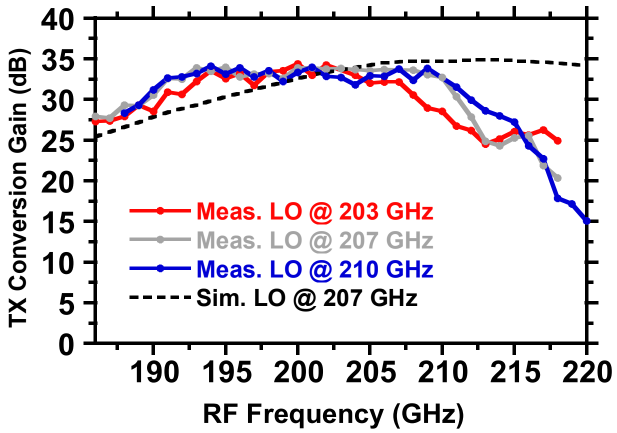
Key link parameters
500 meters range in 50 mm/hr rain; 23 dB/km
20 dB total margins:
packaging loss, obstruction, operating, design, aging
PAs: 63mW =P_{1dB} (per element)
LNAs: 6dB noise figure

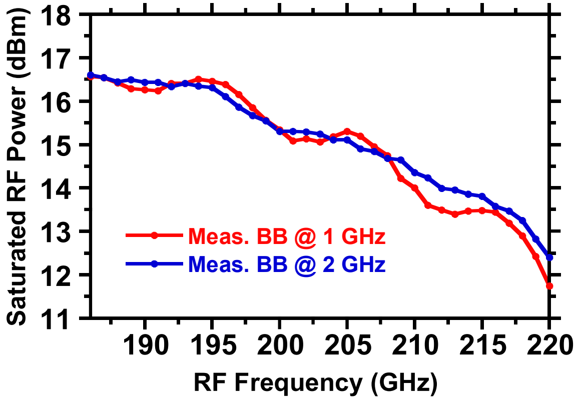
210 GHz Transmitter and Receiver ICs

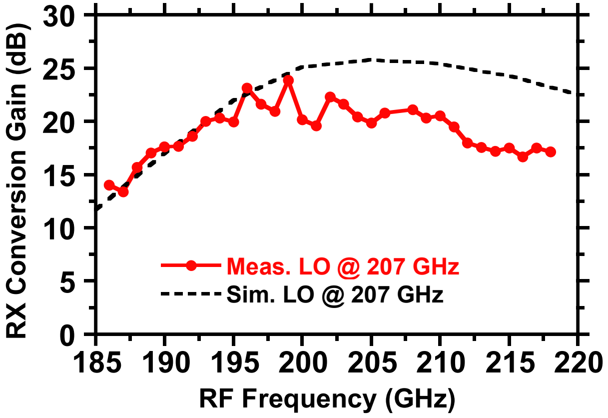
M. **Seo** et al, 2021 IMS; Teledyne 250nm InP HBT

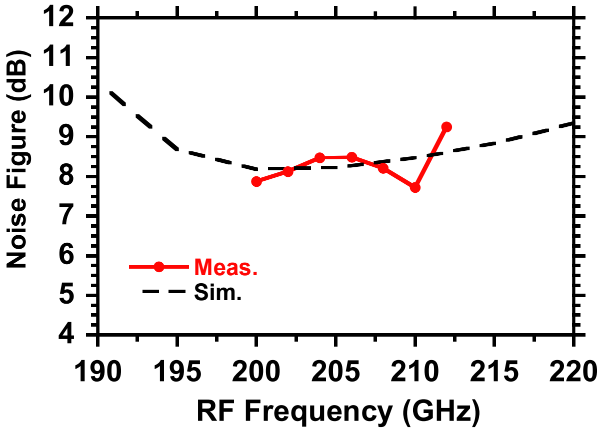




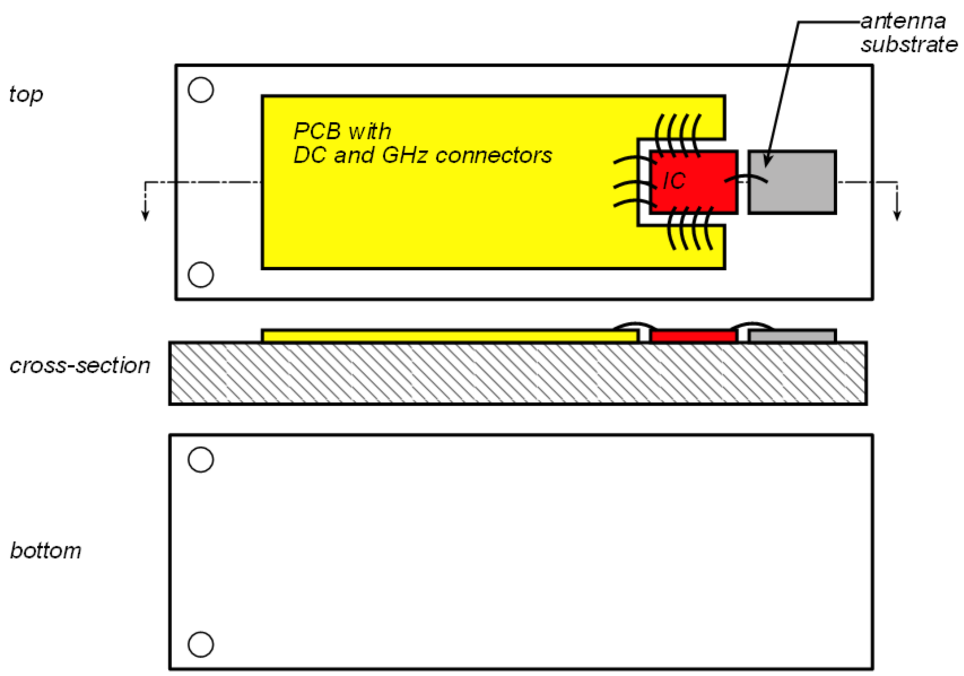


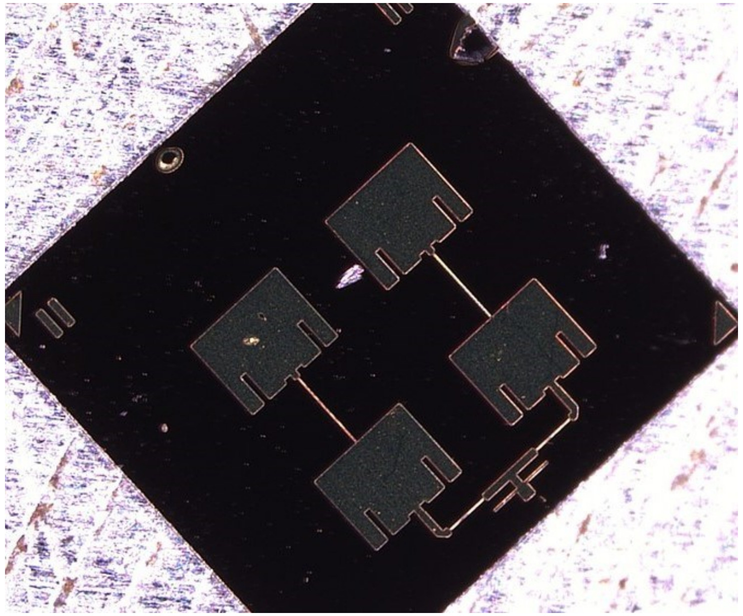


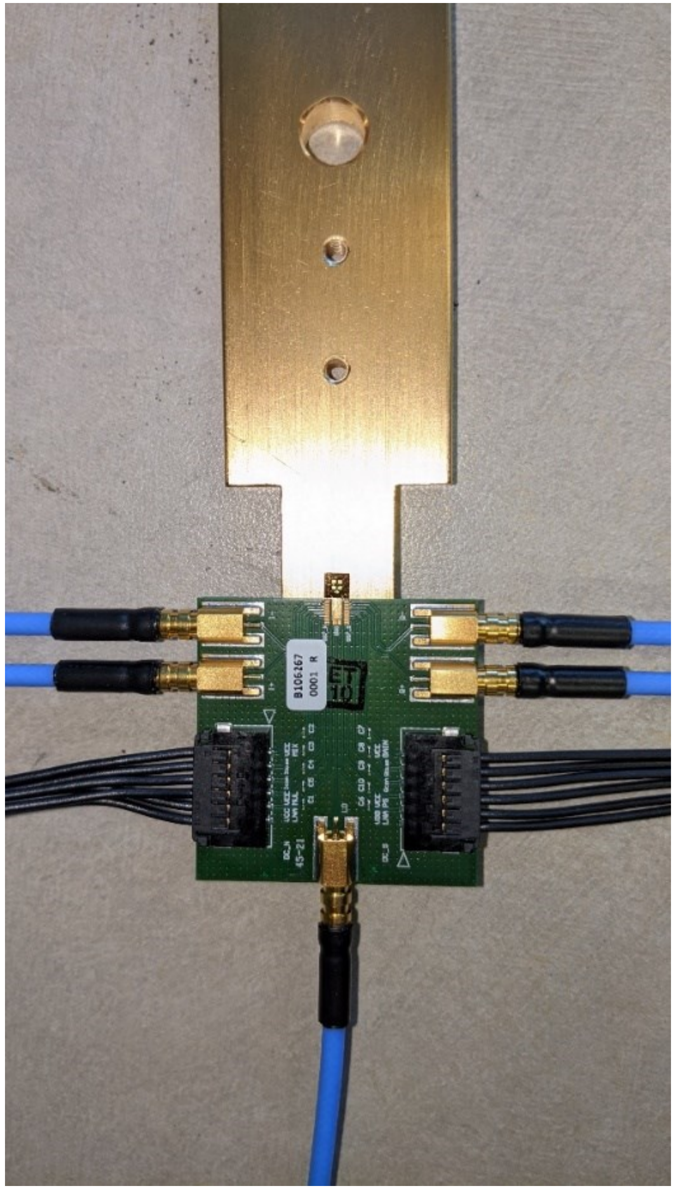


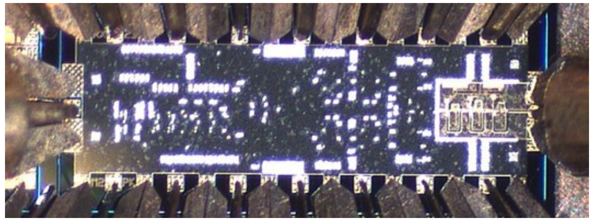


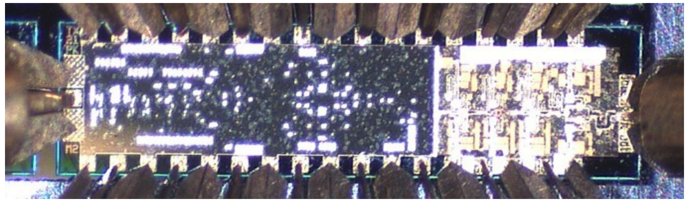
210 GHz MIMO transceiver modules: in development

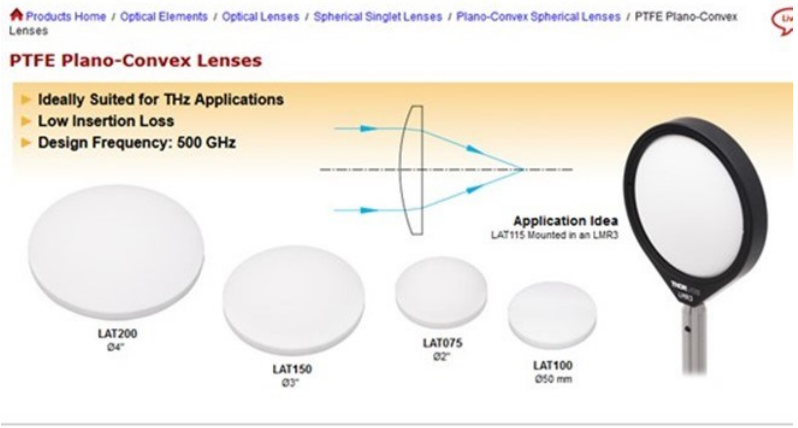








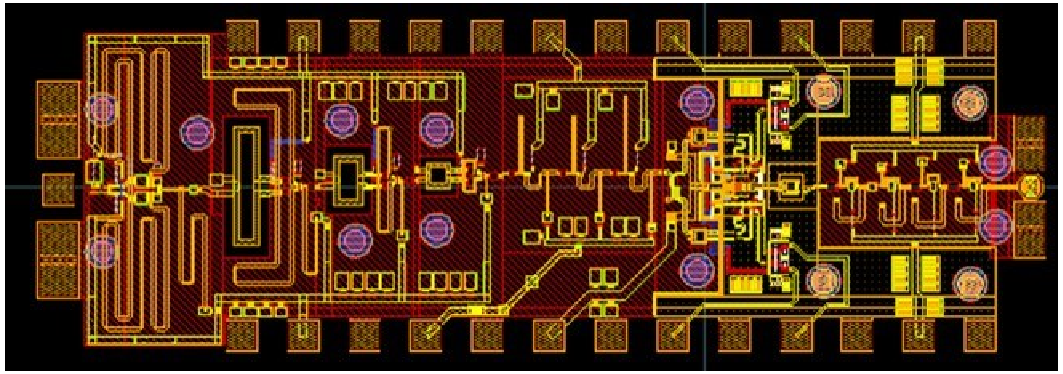




280GHz transmitter and receiver IC designs

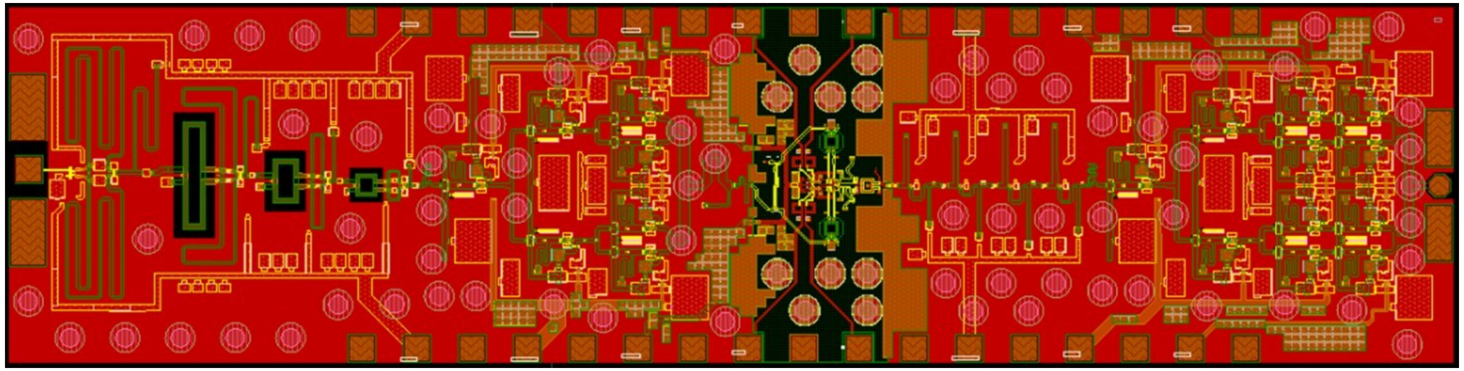
Solyu, Alz, Ahmed, Seo; UCSB/Sungkyunkwan
Teledyne 250nm InP HBT technology

Receiver



simulations: 11dB noise figure, 40GHz bandwidth

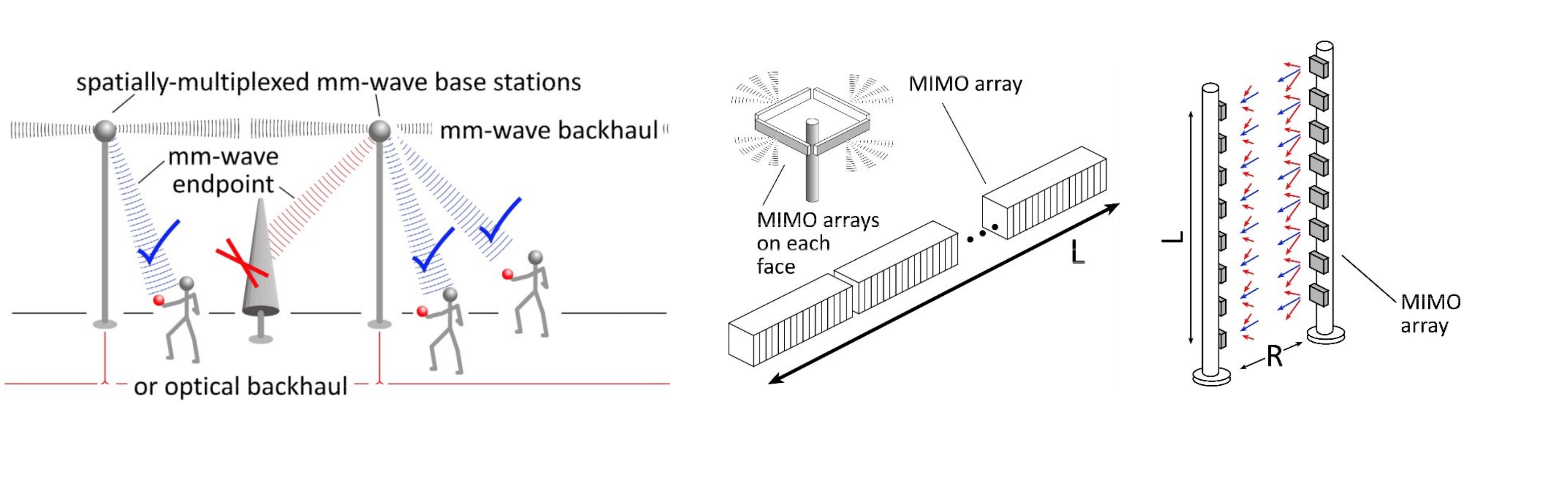
Transmitter



simulations: 17dB saturated output power.

Application: point-point MIMO backhaul links

100-300GHz Wireless



Wireless above 100 GHz

Massive capacities
large available bandwidths
massive spatial multiplexing in base stations and point-point links

Very short range: few 100 meters
short wavelength, high atmospheric losses. Easily-blocked beams.

IC Technology
All-silicon for short ranges below 200 GHz.
SiGe or III-V LNAs and PAs for longer-range links. Just like cell phones today
III-V frequency extenders for 340GHz and beyond

The challenges
computational complexity
packaging: fitting signal channels in very small areas
mesh networking to accommodate beam blockage
driving the technologies to low cost

(backup files follow)

70 GHz spatially multiplexed base station

If we use instead a 70GHz carrier,
the range increases to **70 meters** (vs. **40 meters**)
but the handset becomes **16mm×16mm** (vs. 8mm×8mm),
and the hub array becomes 19mm×612mm (vs. 10mm×328mm)

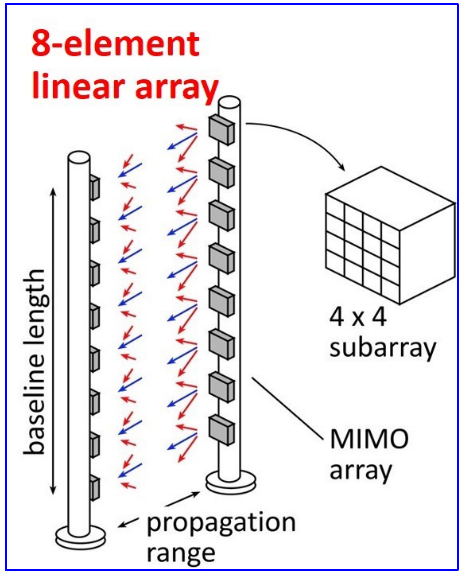
Or, use a 4×4 (**8mm×8mm**) handset array,
and the range becomes ..**about 40 meters**.

Same handset area (more handset elements)→ same link budget
Easier to obtain license for 140±2.5GHz than 70±2.5GHz

75 GHz, 640 Gb/s MIMO backhaul (16QAM)

Why not use a lower-frequency carrier, e.g. 75 GHz ?

Must use at least 16QAM, given 80Gb/s/channel…



8-element 640Gb/s linear array:

requires 16dB$_m$ transmit power/element (P_{out})

requires 3.5m linear array

Similar RF power output, physically larger